

XPT IGBT

tentative

$$V_{CES} = 1200V$$

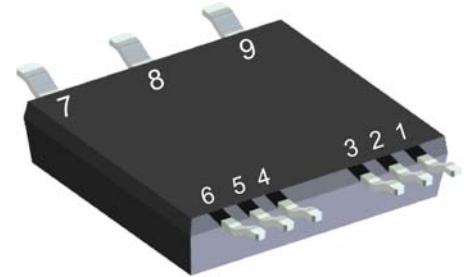
$$I_{C25} = 43A$$

$$V_{CE(sat)} = 1.8V$$

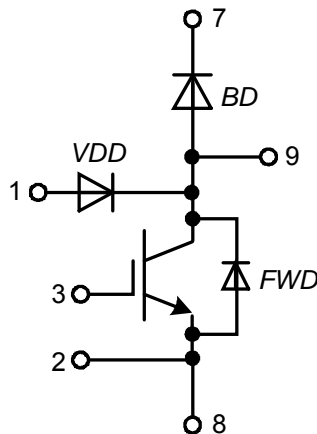
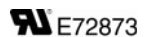
ISOPLUS™ Surface Mount Power Device
 Boost Topology
 XPT IGBT

Part number

IXA30RG1200DHGLB



Backside: isolated



Features / Advantages:

- XPT IGBT
 - low saturation voltage
 - positive temperature coefficient for easy paralleling
 - fast switching
 - short tail current for optimized performance in resonant circuits
- Sonic™ diode
 - fast reverse recovery
 - low operating forward voltage
 - low leakage current
 - low temperature dependency of reverse recovery
- Vcesat detection diode (VDD)
 - integrated into package
 - very fast diode

Applications:

- AC drives
 - brake chopper
- PFC
 - boost chopper
- Switched reluctance drives

Package: SMPD

- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling
- Isolation Voltage: 3000 V~

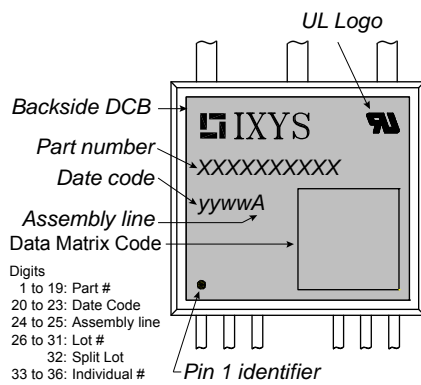
| Free Wheeling Diode FWD | | | | Ratings | | | |
|-------------------------|--|--|--------------------------------|---------|------|---------------|--|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit | |
| V_{RSM} | max. non-repetitive reverse blocking voltage | $T_{VJ} = 25^{\circ}\text{C}$ | | | 1200 | V | |
| V_{RRM} | max. repetitive reverse blocking voltage | $T_{VJ} = 25^{\circ}\text{C}$ | | | 1200 | V | |
| I_R | reverse current, drain current | $V_R = 1200\text{ V}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 30 | μA | |
| | | $V_R = 1200\text{ V}$ | $T_{VJ} = 125^{\circ}\text{C}$ | | 0.5 | mA | |
| V_F | forward voltage drop | $I_F = 30\text{ A}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 2.20 | V | |
| | | | | | | V | |
| | | $I_F = 60\text{ A}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 2.20 | V | |
| | | | $T_{VJ} = 125^{\circ}\text{C}$ | | | V | |
| I_{FAV} | average forward current | $T_C = 80^{\circ}\text{C}$ rectangular $d = 0.5$ | $T_{VJ} = 150^{\circ}\text{C}$ | | 25 | A | |
| V_{FO} | threshold voltage | } for power loss calculation only | $T_{VJ} = 150^{\circ}\text{C}$ | | 1.26 | V | |
| r_F | slope resistance | | | | 28 | m Ω | |
| R_{thJC} | thermal resistance junction to case | | | | 1 | K/W | |
| R_{thCH} | thermal resistance case to heatsink | | | 0.30 | | K/W | |
| P_{tot} | total power dissipation | | $T_C = 25^{\circ}\text{C}$ | | 125 | W | |
| I_{FSM} | max. forward surge current | $t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}; V_R = 0\text{ V}$ | $T_{VJ} = 45^{\circ}\text{C}$ | | 200 | A | |
| C_J | junction capacitance | $V_R = 400\text{ V}$ $f = 1\text{ MHz}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 13 | pF | |

| VCEsat Detection Diode VDD | | | | Ratings | | | |
|----------------------------|--|---|--------------------------------|---------|------|---------------|--|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit | |
| V_{RRM} | max. repetitive reverse blocking voltage | $T_{VJ} = 25^{\circ}\text{C}$ | | | 1200 | V | |
| I_R | reverse current, drain current | $V_{R/D} = 1200\text{ V}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 2 | μA | |
| | | $V_{R/D} = 1200\text{ V}$ | $T_{VJ} = 125^{\circ}\text{C}$ | | 0.03 | mA | |
| V_F | forward voltage drop | $I_F = 1\text{ A}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 2.20 | V | |
| | | | $T_{VJ} = 125^{\circ}\text{C}$ | | 1.80 | V | |
| V_{FO} | threshold voltage | } for power loss calculation only | $T_{VJ} = 150^{\circ}\text{C}$ | | 1.30 | V | |
| r_F | slope resistance | | | | 390 | m Ω | |
| C_J | junction capacitance | $V_R = 400\text{ V}; f = 1\text{ MHz}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | tbd | pF | |
| I_{RM} | max. reverse recovery current | } $V_R = 100\text{ V}; I_F = 1\text{ A}$ $-di/dt = 100\text{ A}/\mu\text{s}$ | $T_{VJ} = 25^{\circ}\text{C}$ | | 2.3 | A | |
| t_{rr} | reverse recovery time | | $T_{VJ} = 125^{\circ}\text{C}$ | | tbd | A | |
| | | | $T_{VJ} = 25^{\circ}\text{C}$ | | 40 | ns | |
| | | | $T_{VJ} = 125^{\circ}\text{C}$ | | tbd | ns | |

| Boost IGBT | | | | Ratings | | | |
|-----------------------|---------------------------------------|--|------|---------|----------|---------------|--|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit | |
| V_{CES} | collector emitter voltage | $T_{VJ} = 25^{\circ}\text{C}$ | | | 1200 | V | |
| V_{GES} | max. DC gate voltage | | | | ± 20 | V | |
| V_{GEM} | max. transient collector gate voltage | | | | ± 30 | V | |
| I_{C25} | collector current | $T_C = 25^{\circ}\text{C}$ | | | 43 | A | |
| I_{C80} | | $T_C = 80^{\circ}\text{C}$ | | | 30 | A | |
| P_{tot} | total power dissipation | $T_C = 25^{\circ}\text{C}$ | | | 147 | W | |
| $V_{CE(sat)}$ | collector emitter saturation voltage | $I_C = 25\text{ A}; V_{GE} = 15\text{ V}$ | | | 1.8 | V | |
| | | | | | 2.1 | V | |
| $V_{GE(th)}$ | gate emitter threshold voltage | $I_C = 1\text{ mA}; V_{GE} = V_{CE}$ | 5.4 | 5.9 | 6.5 | V | |
| I_{CES} | collector emitter leakage current | $V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$ | | | 0.1 | mA | |
| | | | | | 0.1 | mA | |
| I_{GES} | gate emitter leakage current | $V_{GE} = \pm 20\text{ V}$ | | | 500 | nA | |
| $Q_{G(on)}$ | total gate charge | $V_{CE} = 600\text{ V}; V_{GE} = 15\text{ V}; I_C = 25\text{ A}$ | | 76 | | nC | |
| $t_{d(on)}$ | turn-on delay time | inductive load $V_{CE} = 600\text{ V}; I_C = 25\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 39\ \Omega$ | | | | | |
| t_r | current rise time | | | | | | |
| $t_{d(off)}$ | turn-off delay time | | | | | | |
| t_f | current fall time | | | | | | |
| E_{on} | turn-on energy per pulse | | | | | | |
| E_{off} | turn-off energy per pulse | | | | | | |
| R_{BSOA} | reverse bias safe operating area | $V_{GE} = \pm 15\text{ V}; R_G = 39\ \Omega$ | | | | | |
| I_{CM} | | $V_{CEmax} = 1200\text{ V}$ | | | 75 | A | |
| R_{SCSOA} | short circuit safe operating area | $V_{CEmax} = 1200\text{ V}$ | | | | | |
| t_{sc} | short circuit duration | $V_{CE} = 900\text{ V}; V_{GE} = \pm 15\text{ V}$ | | | 10 | μs | |
| I_{sc} | short circuit current | $R_G = 39\ \Omega; \text{non-repetitive}$ | | | 100 | A | |
| R_{thJC} | thermal resistance junction to case | | | | 0.85 | K/W | |
| R_{thCH} | thermal resistance case to heatsink | | | | 0.25 | K/W | |
| Boost Diode BD | | | | | | | |
| V_{RRM} | max. repetitive reverse voltage | $T_{VJ} = 25^{\circ}\text{C}$ | | | 1200 | V | |
| I_{F25} | forward current | $T_C = 25^{\circ}\text{C}$ | | | 48 | A | |
| I_{F80} | | $T_C = 80^{\circ}\text{C}$ | | | 32 | A | |
| V_F | forward voltage | $I_F = 30\text{ A}$ | | | 2.20 | V | |
| | | | | | 1.90 | V | |
| I_R | reverse current | $V_R = V_{RRM}$ | | | 0.03 | mA | |
| | | | | | 0.15 | mA | |
| Q_{rr} | reverse recovery charge | $V_R = 600\text{ V}$ $-di_F/dt = 600\text{ A}/\mu\text{s}$ $I_F = 30\text{ A}; V_{GE} = 0\text{ V}$ | | | | | |
| I_{RM} | max. reverse recovery current | | | | | | |
| t_{rr} | reverse recovery time | | | | | | |
| E_{rec} | reverse recovery energy | | | | | | |
| R_{thJC} | thermal resistance junction to case | | | | 1 | K/W | |
| R_{thCH} | thermal resistance case to heatsink | | | | 0.3 | K/W | |

tentative

| Package SMPD | | Ratings | | | | |
|---------------|--|-------------------------------------|--------------|------|------|--------|
| Symbol | Definition | Conditions | min. | typ. | max. | Unit |
| I_{RMS} | RMS current | per terminal | | | 100 | A |
| T_{stg} | storage temperature | | -55 | | 150 | °C |
| T_{vj} | virtual junction temperature | | -55 | | 150 | °C |
| Weight | | | | 8.5 | | g |
| F_C | mounting force with clip | | 40 | | 130 | N |
| V_{ISOL} | isolation voltage | t = 1 second t = 1 minute | 3000 2500 | | | V V |
| | | 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA | | | | |
| $d_{Spp/App}$ | creepage distance on surface striking distance through air | | 1.6 | | | mm |
| $d_{Spb/Apb}$ | | | 4.0 | | | mm |
| | | terminal to terminal | | | | |
| | | terminal to backside | | | | |



Part number

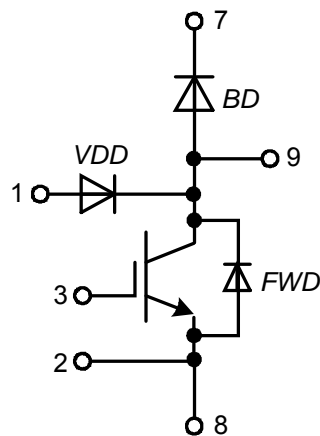
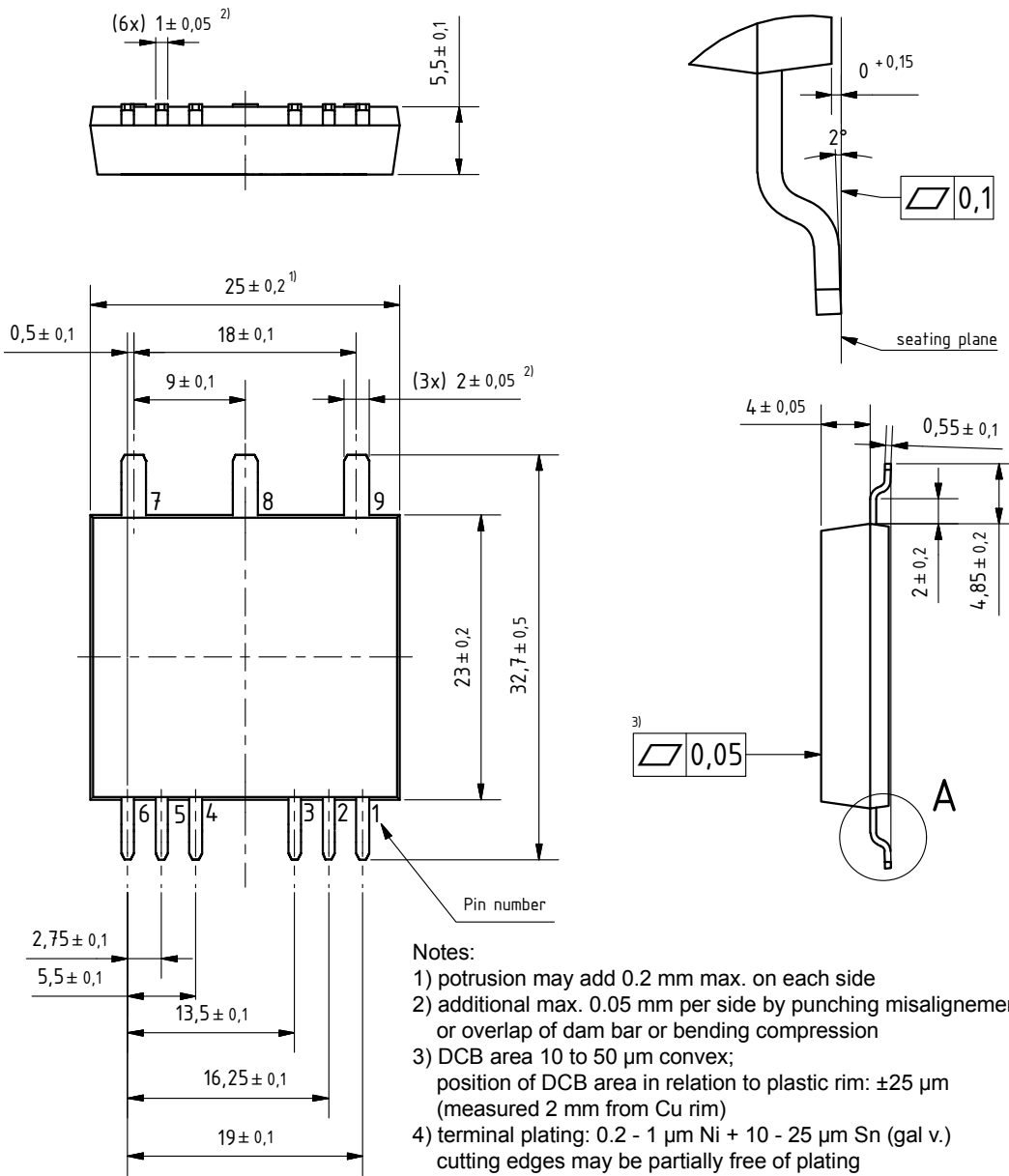
- I = IGBT
- X = XPT IGBT
- A = Gen 1 / std
- 30 = Current Rating [A]
- RG = boost configuration
- 1200 = Reverse Voltage [V]
- D = IGBT
- H = XPT IGBT
- G = Gen 1 / std
- LB = SMPD-B

| Ordering | Part Number | Marking on Product | Delivery Mode | Quantity | Code No. |
|-------------|----------------------|--------------------|---------------|----------|----------|
| Standard | IXA30RG1200DHGLB | IXA30RG1200DHGLB | Blister | 45 | 512356 |
| Alternative | IXA30RG1200DHGLB-TRR | IXA30RG1200DHGLB | Tape & Reel | 200 | 511654 |

| Similar Part | Package | Voltage class |
|------------------|---------|---------------|
| IXA20RG1200DHGLB | SMPD-B | 1200 |
| IXA40RG1200DHGLB | SMPD-B | 1200 |

Outlines SMPD

A (8 : 1)



Boost IGBT

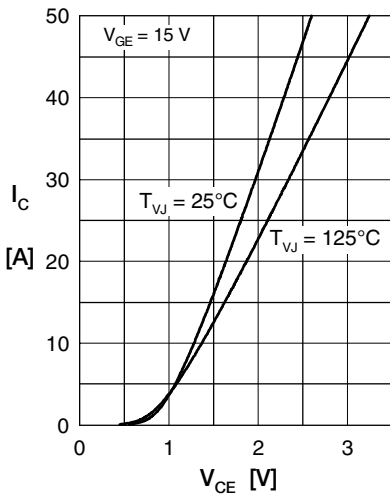


Fig. 1 Typ. output characteristics

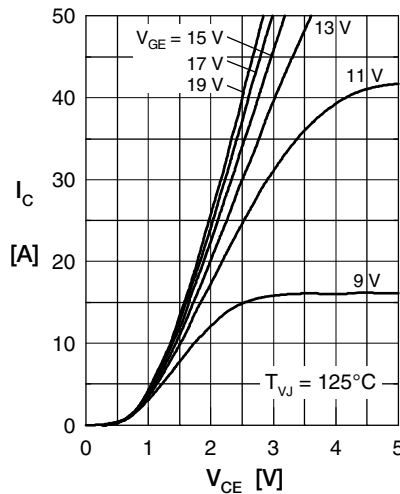


Fig. 2 Typ. output characteristics

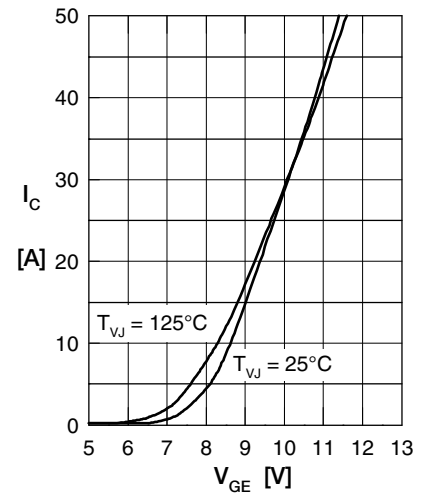


Fig. 3 Typ. transfer characteristics

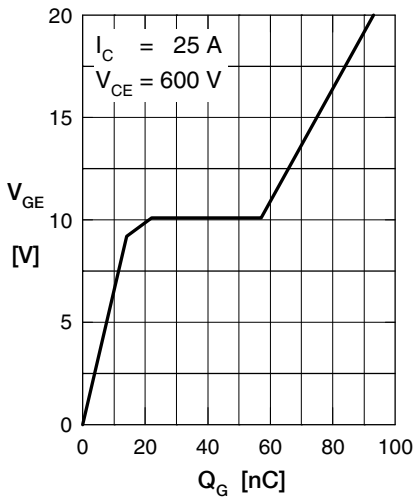


Fig. 4 Typ. turn-on gate charge

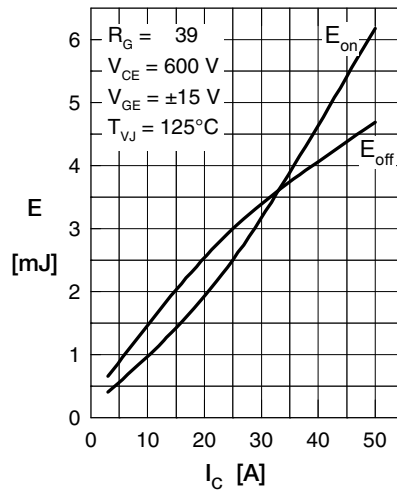


Fig. 5 Typ. switching energy versus collector current

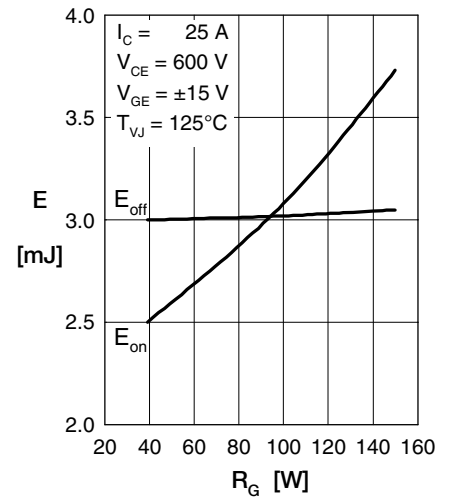


Fig. 6 Typ. switching energy versus gate resistance

Fig. 7 Typ. transient thermal impedance junction to case

Boost Diode BD

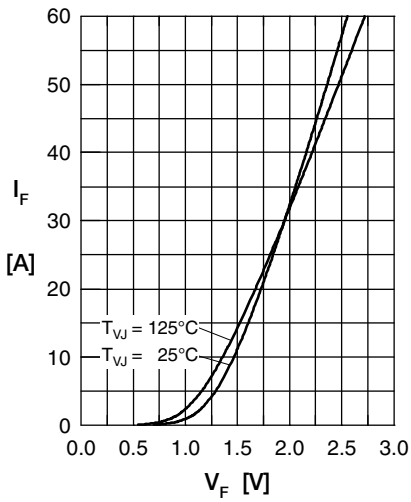


Fig. 1 Typ. Forward current versus V_F

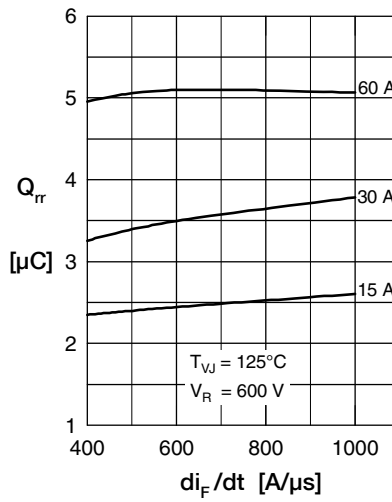


Fig. 2 Typ. reverse recov.charge Q_{rr} versus di/dt

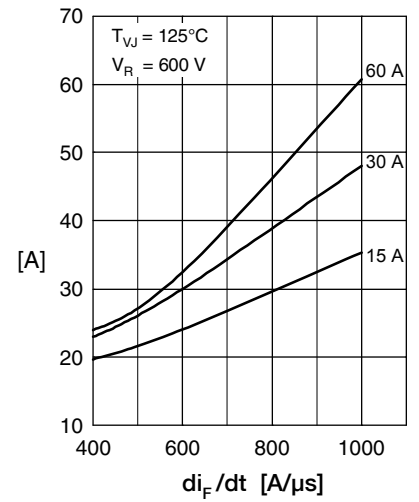


Fig. 3 Typ. peak reverse current I_{RM} versus di/dt

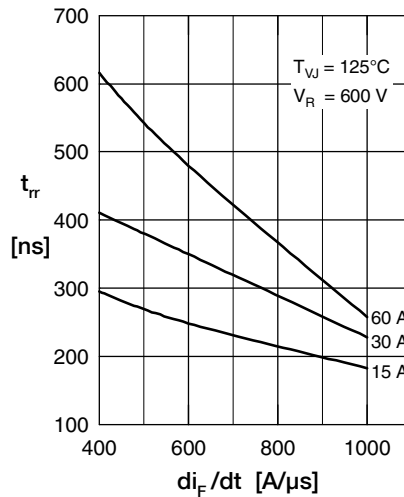


Fig. 4 Dynamic parameters Q_{rr} , I_{RM} versus di/dt

Fig. 5 Typ. recovery time t_{rr} versus di/dt

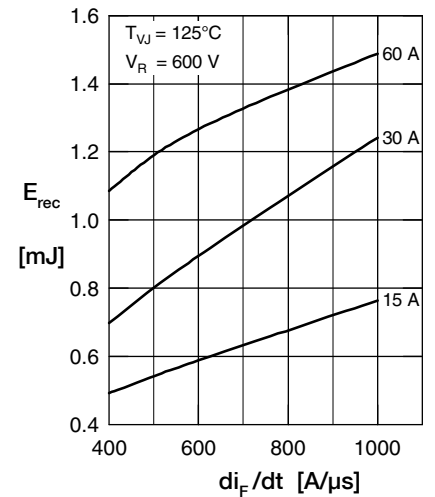


Fig. 6 Typ. recovery energy E_{rec} versus di/dt

Fig. 7 Typ. transient thermal impedance junction to case



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